

# PSoC® 4: PSoC 4100S Datasheet

# Programmable System-on-Chip (PSoC)

## **General Description**

PSoC<sup>®</sup> 4 is a scalable and reconfigurable platform architecture for a family of programmable embedded system controllers with an ARM<sup>®</sup> Cortex™-M0+ CPU. It combines programmable and reconfigurable analog and digital blocks with flexible automatic routing. The PSoC 4100S product family is a member of the PSoC 4 platform architecture. It is a combination of a microcontroller with standard communication and timing peripherals, a capacitive touch-sensing system (CapSense) with best-in-class performance, programmable general-purpose continuous-time and switched-capacitor analog blocks, and programmable connectivity. PSoC 4100S products will be upward compatible with members of the PSoC 4 platform for new applications and design needs.

#### **Features**

#### 32-bit MCU Subsystem

- 48-MHz ARM Cortex-M0+ CPU with single-cycle multiply
- Up to 64 KB of flash with Read Accelerator
- Up to 8 KB of SRAM

#### **Programmable Analog**

- Two opamps with reconfigurable high-drive external and high-bandwidth internal drive and Comparator modes and ADC input buffering capability. Opamps can operate in Deep Sleep low-power mode.
- 12-bit 1-Msps SAR ADC with differential and single-ended modes, and Channel Sequencer with signal averaging
- Single-slope 10-bit ADC function provided by a capacitance sensing block
- Two current DACs (IDACs) for general-purpose or capacitive sensing applications on any pin
- Two low-power comparators that operate in Deep Sleep low-power mode

#### **Programmable Digital**

■ Programmable logic blocks allowing Boolean operations to be performed on port inputs and outputs

#### Low-Power 1.71-V to 5.5-V Operation

■ Deep Sleep mode with operational analog and 2.5-µA digital system current

### **Capacitive Sensing**

- Cypress CapSense Sigma-Delta (CSD) provides best-in-class signal-to-noise ratio (SNR) (>5:1) and water tolerance
- Cypress-supplied software component makes capacitive sensing design easy
- Automatic hardware tuning (SmartSense<sup>™</sup>)

### **LCD Drive Capability**

■ LCD segment drive capability on GPIOs

#### **Serial Communication**

Three independent run-time reconfigurable Serial Communication Blocks (SCBs) with re-configurable I<sup>2</sup>C, SPI, or UART functionality

#### **Timing and Pulse-Width Modulation**

- Five 16-bit timer/counter/pulse-width modulator (TCPWM) blocks
- Center-aligned, Edge, and Pseudo-random modes
- Comparator-based triggering of Kill signals for motor drive and other high-reliability digital logic applications
- Quadrature decoder

## **Up to 36 Programmable GPIO Pins**

- 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball WLCSP packages
- Any GPIO pin can be CapSense, analog, or digital
- Drive modes, strengths, and slew rates are programmable

#### **Clock Sources**

- 32-kHz Watch Crystal Oscillator (WCO)
- ±2% Internal Main Oscillator (IMO)
- 32-kHz Internal Low-power Oscillator (ILO)

#### **PSoC Creator Design Environment**

- Integrated Development Environment (IDE) provides schematic design entry and build (with analog and digital automatic routing)
- Applications Programming Interface (API) component for all fixed-function and programmable peripherals

#### **Industry-Standard Tool Compatibility**

 After schematic entry, development can be done with ARM-based industry-standard development tools

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## **Development Support**

Cypress provides a wealth of data at www.cypress.com to help you to select the right PSoC device for your design, and to help you to quickly and effectively integrate the device into your design. For a comprehensive list of resources, see the knowledge base article KBA86521, How to Design with PSoC 3, PSoC 4, and PSoC 5LP. Following is an abbreviated list for PSoC 4:

- Overview: PSoC Portfolio, PSoC Roadmap
- Product Selectors: PSoC 1, PSoC 3, PSoC 4, PSoC 5LP In addition, PSoC Creator includes a device selection tool.
- Application notes: Cypress offers a large number of PSoC application notes covering a broad range of topics, from basic to advanced level. Recommended application notes for getting started with PSoC 4 are:
  - □ AN79953: Getting Started With PSoC 4
- □ AN88619: PSoC 4 Hardware Design Considerations
- □ AN86439: Using PSoC 4 GPIO Pins
- □ AN57821: Mixed Signal Circuit Board Layout
- □ AN81623: Digital Design Best Practices
- AN73854: Introduction To Bootloaders
- □ AN89610: ARM Cortex Code Optimization
- □ AN85951: PSoC® 4 and PSoC Analog Coprocessor CapSense® Design Guide
- Technical Reference Manual (TRM) is in two documents:
  - □ Architecture TRM details each PSoC 4 functional block.
  - Registers TRM describes each of the PSoC 4 registers.
- Development Kits:
  - □ CY8CKIT-041-41XX PSoC 4100S CapSense Pioneer Kit, is an easy-to-use and inexpensive development platform. This kit includes connectors for Arduino<sup>™</sup> compatible shields.

The MiniProg3 device provides an interface for flash programming and debug.

#### ■ Software User Guide:

□ A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

#### ■ Component Datasheets:

☐ The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component datasheets provide all the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

#### ■ Online:

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

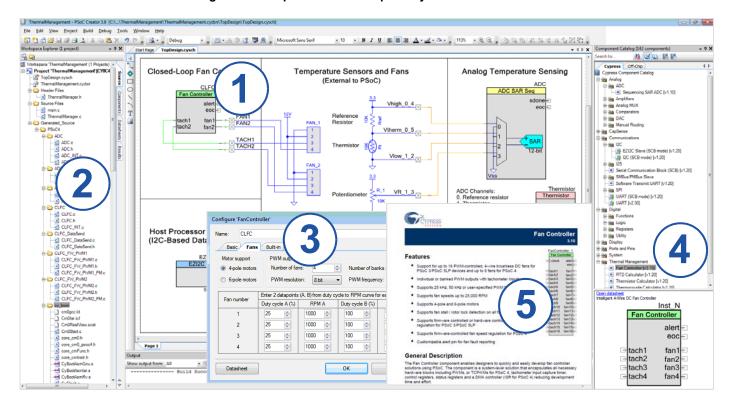


### **PSoC Creator**

PSoC Creator is a free Windows-based Integrated Design Environment (IDE). It enables concurrent hardware and firmware design of PSoC 3, PSoC 4, and PSoC 5LP based systems. Create designs using classic, familiar schematic capture supported by over 100 pre-verified, production-ready PSoC Components; see the list of component datasheets. With PSoC Creator, you can:

- 1. Drag and drop component icons to build your hardware system design in the main design workspace
- Codesign your application firmware with the PSoC hardware, using the PSoC Creator IDE C compiler
- 3. Configure components using the configuration tools
- 4. Explore the library of 100+ components
- 5. Review component datasheets

Figure 1. Multiple-Sensor Example Project in PSoC Creator





## **Contents**

Functional Definition	<del>6</del>
CPU and Memory Subsystem	6
System Resources	
Analog Blocks	7
Programmable Digital Blocks	
Fixed Function Digital	7
GPIO	
Special Function Peripherals	8
Pinouts	
Alternate Pin Functions	
Power	13
Mode 1: 1.8 V to 5.5 V External Supply	13
Mode 2: 1.8 V ±5% External Supply	13
Electrical Specifications	
Absolute Maximum Ratings	14
Device Level Specifications	
Analog Peripherals	18

Digital Peripherals	25
Memory	
System Resources	
Ordering Information	
Packaging	
Package Diagrams	
Acronyms	
Document Conventions	
Units of Measure	
Revision History	
Sales, Solutions, and Legal Information	
Worldwide Sales and Design Support	
Products	
PSoC® Solutions	41
Cypress Developer Community	
Technical Support	



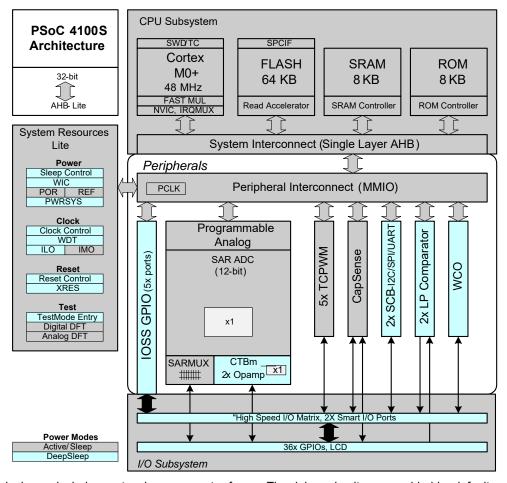


Figure 2. Block Diagram

PSoC 4100S devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4100S devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4100S provides a level of security not possible with multi-chip application solutions or with microcontrollers.

It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging. Thus firmware control of debugging cannot be over-ridden without erasing the firmware thus providing security.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are disabled when maximum device security is enabled. Therefore, PSoC 4100S, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4100S allows the customer to make.



#### **Functional Definition**

### CPU and Memory Subsystem

#### CPU

The Cortex-M0+ CPU in the PSoC 4100S is part of the 32-bit MCU subsystem, which is optimized for low-power operation with extensive clock gating. Most instructions are 16 bits in length and the CPU executes a subset of the Thumb-2 instruction set. It includes a nested vectored interrupt controller (NVIC) block with eight interrupt inputs and also includes a Wakeup Interrupt Controller (WIC). The WIC can wake the processor from Deep Sleep mode, allowing power to be switched off to the main processor when the chip is in Deep Sleep mode.

The CPU also includes a debug interface, the serial wire debug (SWD) interface, which is a two-wire form of JTAG. The debug configuration used for PSoC 4100S has four breakpoint (address) comparators and two watchpoint (data) comparators.

#### Flash

The PSoC 4100S device has a flash module with a flash accelerator, tightly coupled to the CPU to improve average access times from the flash block. The low-power flash block is designed to deliver two wait-state (WS) access time at 48 MHz. The flash accelerator delivers 85% of single-cycle SRAM access performance on average.

#### **SRAM**

Eight KB of SRAM are provided with zero wait-state access at 48 MHz.

#### **SROM**

An 8 KB supervisory ROM that contains boot and configuration routines is provided.

#### System Resources

#### Power System

The power system is described in detail in the section Power on page 13. It provides assurance that voltage levels are as required for each respective mode and either delays mode entry (for example, on power-on reset (POR)) until voltage levels are as required for proper functionality, or generates resets (for example, on brown-out detection). The PSoC 4100S operates with a single external supply over the range of either 1.8 V ±5% (externally regulated) or 1.8 to 5.5 V (internally regulated) and has three different power modes, transitions between which are managed by the power system. The PSoC 4100S provides Active, Sleep, and Deep Sleep low-power modes.

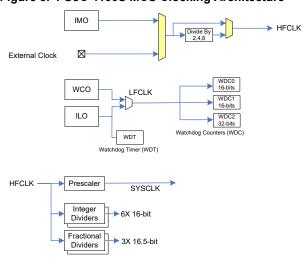
All subsystems are operational in Active mode. The CPU subsystem (CPU, flash, and SRAM) is clock-gated off in Sleep mode, while all peripherals and interrupts are active with instantaneous wake-up on a wake-up event. In Deep Sleep mode, the high-speed clock and associated circuitry is switched off; wake-up from this mode takes 35 µs. The opamps can remain operational in Deep Sleep mode.

#### Clock System

The PSoC 4100S clock system is responsible for providing clocks to all subsystems that require clocks and for switching between different clock sources without glitching. In addition, the clock system ensures that there are no metastable conditions.

The clock system for the PSoC 4100S consists of the internal main oscillator (IMO), internal low-frequency oscillator (ILO), a 32 kHz Watch Crystal Oscillator (WCO) and provision for an external clock. Clock dividers are provided to generate clocks for peripherals on a fine-grained basis. Fractional dividers are also provided to enable clocking of higher data rates for UARTs.

Figure 3. PSoC 4100S MCU Clocking Architecture



The HFCLK signal can be divided down to generate synchronous clocks for the analog and digital peripherals. There are eight clock dividers for the PSoC 4100S; two of those are fractional dividers. The 16-bit capability allows flexible generation of fine-grained frequency values and is fully supported in PSoC Creator

#### IMO Clock Source

The IMO is the primary source of internal clocking in the PSoC 4100S. It is trimmed during testing to achieve the specified accuracy. The IMO default frequency is 24 MHz and it can be adjusted from 24 to 48 MHz in steps of 4 MHz. The IMO tolerance with Cypress-provided calibration settings is ±2%.

#### ILO Clock Source

The ILO is a very low power, nominally 40-kHz oscillator, which is primarily used to generate clocks for the watchdog timer (WDT) and peripheral operation in Deep Sleep mode. ILO-driven counters can be calibrated to the IMO to improve accuracy. Cypress provides a software component, which does the calibration.

#### Watch Crystal Oscillator (WCO)

The PSoC 4100S clock subsystem also implements a low-frequency (32-kHz watch crystal) oscillator that can be used for precision timing applications. The WCO block allows locking the IMO to the 32-kHz oscillator.

#### Watchdog Timer and Counters

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the set timeout occurs. The watchdog reset is recorded in a Reset Cause register, which is firmware readable. The Watchdog counters can be used to implement a Real-Time clock using the 32-kHz WCO.



#### Reset

The PSoC 4100S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

#### Analog Blocks

#### 12-bit SAR ADC

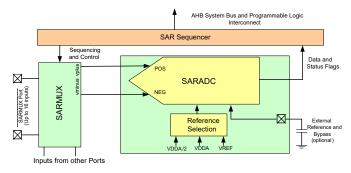
The 12-bit, 1-Msps SAR ADC can operate at a maximum clock rate of 18 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion.

The Sample-and-Hold (S/H) aperture is programmable allowing the gain bandwidth requirements of the amplifier driving the SAR inputs, which determine its settling time, to be relaxed if required. It is possible to provide an external bypass (through a fixed pin location) for the internal reference amplifier.

The SAR is connected to a fixed set of pins through an 8-input sequencer. The sequencer cycles through selected channels autonomously (sequencer scan) with zero switching overhead (that is, aggregate sampling bandwidth is equal to 1 Msps whether it is for a single channel or distributed over several channels). The sequencer switching is effected through a state machine or through firmware driven switching. A feature provided by the sequencer is buffering of each channel to reduce CPU interrupt service requirements. To accommodate signals with varying source impedance and frequency, it is possible to have different sample times programmable for each channel. Also, signal range specification through a pair of range registers (low and high range values) is implemented with a corresponding out-of-range interrupt if the digitized value exceeds the programmed range; this allows fast detection of out-of-range values without the necessity of having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software.

The SAR is not available in Deep Sleep mode as it requires a high-speed clock (up to 18 MHz). The SAR operating range is 1.71 V to 5.5 V.

Figure 4. SAR ADC



Two Opamps (Continuous-Time Block; CTB)

The PSoC 4100S has two opamps with Comparator modes which allow most common analog functions to be performed on-chip eliminating external components; PGAs, Voltage Buffers, Filters, Trans-Impedance Amplifiers, and other functions can be realized, in some cases with external passives. saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the Sample-and-Hold circuit of the ADC without requiring external buffering.

#### Low-power Comparators (LPC)

The PSoC 4100S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

#### Current DACs

The PSoC 4100S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

#### Analog Multiplexed Buses

The PSoC 4100S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

#### **Programmable Digital Blocks**

The Smart I/O block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

#### **Fixed Function Digital**

#### Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4100S.



Serial Communication Block (SCB)

The PSoC 4100S has three serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

I<sup>2</sup>C Mode: The hardware I<sup>2</sup>C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EZI2C that creates a mailbox address range in the memory of the PSoC 4100S and effectively reduces I<sup>2</sup>C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I<sup>2</sup>C peripheral is compatible with the I<sup>2</sup>C Standard-mode and Fast-mode devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual (UM10204). The I<sup>2</sup>C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4100S is not completely compliant with the I<sup>2</sup>C spec in the following respect:

GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I<sup>2</sup>C system.

**UART Mode**: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

**SPI Mode**: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.

#### **GPIO**

The PSoC 4100S has up to 36 GPIOs. The GPIO block implements the following:

- Eight drive modes:
  - ☐ Analog input mode (input and output buffers disabled)
  - □ Input only
  - □ Weak pull-up with strong pull-down
  - ☐ Strong pull-up with weak pull-down
  - □ Open drain with strong pull-down
  - □ Open drain with strong pull-up
  - ☐ Strong pull-up with strong pull-down
  - □ Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve EMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 2 and 3). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4100S).

#### **Special Function Peripherals**

#### CapSense

CapSense is supported in the PSoC 4100S through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and ground to null out power-supply related noise.

#### LCD Segment Drive

The PSoC 4100S has an LCD controller, which can drive up to 4 commons and up to 32 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).



## **Pinouts**

Table 1 provides the pin list for PSoC 4100S for the 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball CSP packages. All port pins support GPIO.

Table 1. Pin List

48-	TQFP	44-	TQFP	40	-QFN	32-	QFN	35-CSP	
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
28	P0.0	24	P0.0	22	P0.0	17	P0.0	C3	P0.0
29	P0.1	25	P0.1	23	P0.1	18	P0.1	A5	P0.1
30	P0.2	26	P0.2	24	P0.2	19	P0.2	A4	P0.2
31	P0.3	27	P0.3	25	P0.3	20	P0.3	A3	P0.3
32	P0.4	28	P0.4	26	P0.4	21	P0.4	В3	P0.4
33	P0.5	29	P0.5	27	P0.5	22	P0.5	A6	P0.5
34	P0.6	30	P0.6	28	P0.6	23	P0.6	B4	P0.6
35	P0.7	31	P0.7	29	P0.7			B5	P0.7
36	XRES	32	XRES	30	XRES	24	XRES	B6	XRES
37	VCCD	33	VCCD	31	VCCD	25	VCCD	A7	VCCD
38	VSSD			DN	VSSD	26	VSSD	B7	VSS
39	VDDD	34	VDDD	32	VDDD			C7	VDD
40	VDDA	35	VDDA	33	VDDA	27	VDD	C7	VDD
41	VSSA	36	VSSA	34	VSSA	28	VSSA	B7	VSS
42	P1.0	37	P1.0	35	P1.0	29	P1.0	C4	P1.0
43	P1.1	38	P1.1	36	P1.1	30	P1.1	C5	P1.1
44	P1.2	39	P1.2	37	P1.2	31	P1.2	C6	P1.2
45	P1.3	40	P1.3	38	P1.3	32	P1.3	D7	P1.3
46	P1.4	41	P1.4	39	P1.4			D4	P1.4
47	P1.5	42	P1.5					D5	P1.5
48	P1.6	43	P1.6					D6	P1.6
1	P1.7/VREF	44	P1.7/VREF	40	P1.7/VREF	1	P1.7/VREF	E7	P1.7/VREF
		1	VSSD						
2	P2.0	2	P2.0	1	P2.0	2	P2.0		
3	P2.1	3	P2.1	2	P2.1	3	P2.1		
4	P2.2	4	P2.2	3	P2.2	4	P2.2	D3	P2.2
5	P2.3	5	P2.3	4	P2.3	5	P2.3	E4	P2.3
6	P2.4	6	P2.4	5	P2.4			E5	P2.4
7	P2.5	7	P2.5	6	P2.5	6	P2.5	E6	P2.5
8	P2.6	8	P2.6	7	P2.6	7	P2.6	E3	P2.6
9	P2.7	9	P2.7	8	P2.7	8	P2.7	E2	P2.7
10	VSSD	10	VSSD	9	VSSD				
12	P3.0	11	P3.0	10	P3.0	9	P3.0	E1	P3.0
13	P3.1	12	P3.1	11	P3.1	10	P3.1	D2	P3.1
14	P3.2	13	P3.2	12	P3.2	11	P3.2	D1	P3.2
16	P3.3	14	P3.3	13	P3.3	12	P3.3	C1	P3.3



Table 1. Pin List (continued)

48-T	QFP	44-TQFP		40-	QFN	32-0	QFN	35-	CSP
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
17	P3.4	15	P3.4	14	P3.4			C2	P3.4
18	P3.5	16	P3.5	15	P3.5				
19	P3.6	17	P3.6	16	P3.6				
20	P3.7	18	P3.7	17	P3.7				
21	VDDD	19	VDDD						
22	P4.0	20	P4.0	18	P4.0	13	P4.0	B1	P4.0
23	P4.1	21	P4.1	19	P4.1	14	P4.1	B2	P4.1
24	P4.2	22	P4.2	20	P4.2	15	P4.2	A2	P4.2
25	P4.3	23	P4.3	21	P4.3	16	P4.3	A1	P4.3

Note Pins 11, 15, 26, and 27 are No Connects (NC) on the 48-pin TQFP.

## Descriptions of the Power pins are as follows:

VDDD: Power supply for the digital section.

VDDA: Power supply for the analog section.

VSSD, VSSA: Ground pins for the digital and analog sections respectively.

VCCD: Regulated digital supply (1.8 V ±5%)

VDD: Power supply to all sections of the chip

VSS: Ground for all sections of the chip



### **Alternate Pin Functions**

Each Port pin has can be assigned to one of multiple functions; it can, for instance, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in Table 2.

**Table 2. Alternate Pin Functions** 

Port/Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P0.0	lpcomp.in_p[0]				tcpwm.tr_in[0]	scb[2].i2c_scl:0	scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]				tcpwm.tr_in[1]	scb[2].i2c_sda:0	scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]						scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]						scb[2].spi_select0
P0.4	wco.wco_in			scb[1].uart_rx:0	scb[2].uart_rx:0	scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco.wco_out			scb[1].uart_tx:0	scb[2].uart_tx:0	scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6			srss.ext_clk	scb[1].uart_cts:0	scb[2].uart_tx:1		scb[1].spi_clk:1
P0.7			tcpwm.line[0]:2	scb[1].uart_rts:0			scb[1].spi_select0:1
P1.0	ctb0_oa0+		tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1	ctb0_oa0-		tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2	ctb0_oa0_out		tcpwm.line[3]:1	scb[0].uart_cts:1	tcpwm.tr_in[2]	scb[2].i2c_scl:1	scb[0].spi_clk:1
P1.3	ctb0_oa1_out		tcpwm.line_compl[3]:1	scb[0].uart_rts:1	tcpwm.tr_in[3]	scb[2].i2c_sda:1	scb[0].spi_select0:1
P1.4	ctb0_oa1-						scb[0].spi_select1:1
P1.5	ctb0_oa1+						scb[0].spi_select2:1
P1.6	ctb0_oa0+						scb[0].spi_select3:1
P1.7	ctb0_oa1+ sar_ext_vref0 sar_ext_vref1						scb[2].spi_clk
P2.0	sarmux[0]	Smartlo[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1	sarmux[1]	Smartlo[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2	sarmux[2]	Smartlo[0].io[2]					scb[1].spi_clk:2
P2.3	sarmux[3]	Smartlo[0].io[3]					scb[1].spi_select0:2
P2.4	sarmux[4]	Smartlo[0].io[4]	tcpwm.line[0]:1				scb[1].spi_select1:1
P2.5	sarmux[5]	Smartlo[0].io[5]	tcpwm.line_compl[0]:1				scb[1].spi_select2:1
P2.6	sarmux[6]	Smartlo[0].io[6]	tcpwm.line[1]:1				scb[1].spi_select3:1
P2.7	sarmux[7]	Smartlo[0].io[7]	tcpwm.line_compl[1]:1			lpcomp.comp[0]:1	scb[2].spi_mosi
P3.0		Smartlo[1].io[0]	tcpwm.line[0]:0	scb[1].uart_rx:1		scb[1].i2c_scl:2	scb[1].spi_mosi:0



Table 2. Alternate Pin Functions (continued)

Port/Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P3.1		Smartlo[1].io[1]	tcpwm.line_compl[0]:0	scb[1].uart_tx:1		scb[1].i2c_sda:2	scb[1].spi_miso:0
P3.2		Smartlo[1].io[2]	tcpwm.line[1]:0	scb[1].uart_cts:1		cpuss.swd_data	scb[1].spi_clk:0
P3.3		Smartlo[1].io[3]	tcpwm.line_compl[1]:0	scb[1].uart_rts:1		cpuss.swd_clk	scb[1].spi_select0:0
P3.4		Smartlo[1].io[4]	tcpwm.line[2]:0		tcpwm.tr_in[6]		scb[1].spi_select1:0
P3.5		Smartlo[1].io[5]	tcpwm.line_compl[2]:0				scb[1].spi_select2:0
P3.6		Smartlo[1].io[6]	tcpwm.line[3]:0				scb[1].spi_select3:0
P3.7		Smartlo[1].io[7]	tcpwm.line_compl[3]:0			lpcomp.comp[1]:1	scb[2].spi_miso
P4.0	csd.vref_ext			scb[0].uart_rx:0		scb[0].i2c_scl:1	scb[0].spi_mosi:0
P4.1	csd.cshieldpads			scb[0].uart_tx:0		scb[0].i2c_sda:1	scb[0].spi_miso:0
P4.2	csd.cmodpad			scb[0].uart_cts:0		lpcomp.comp[0]:0	scb[0].spi_clk:0
P4.3	csd.csh_tank			scb[0].uart_rts:0		lpcomp.comp[1]:0	scb[0].spi_select0:0

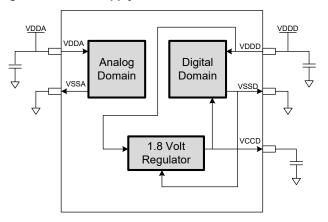
Document Number: 002-00122 Rev. \*L Page 12 of 41



#### **Power**

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4100S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the  $V_{DD}$  input.

Figure 5. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is 1.8 V ±5% (externally regulated; 1.71 to 1.89, internal regulator bypassed).

### Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4100S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4100S supplies the internal logic and its output is connected to the  $V_{CCD}$  pin. The VCCD pin must be bypassed to ground via an external capacitor (0.1  $\mu F;\ X5R$  ceramic or better) and must not be connected to anything else.

### Mode 2: 1.8 V ±5% External Supply

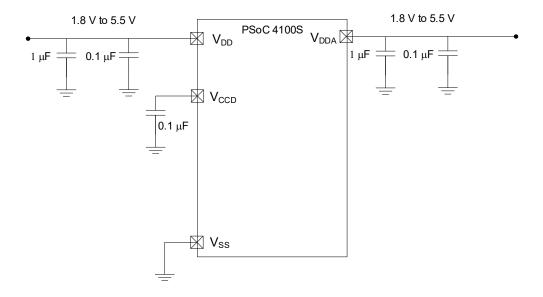
In this mode, the PSoC 4100S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the VDD and VCCD pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from VDDD to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- $\mu$ F range, in parallel with a smaller capacitor (0.1  $\mu$ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

Figure 6 shows an example of a bypass scheme.

Figure 6. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active

Power supply bypass connections example





# **Electrical Specifications**

## **Absolute Maximum Ratings**

# Table 3. Absolute Maximum Ratings<sup>[1]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID1	V <sub>DDD_ABS</sub>	Digital supply relative to V <sub>SS</sub>	-0.5	_	6		_
SID2	V <sub>CCD_ABS</sub>	Direct digital core voltage input relative to V <sub>SS</sub>	-0.5	-	1.95	V	-
SID3	V <sub>GPIO_ABS</sub>	GPIO voltage	-0.5	_	V <sub>DD</sub> +0.5		-
SID4	I <sub>GPIO_ABS</sub>	Maximum current per GPIO	-25	_	25		-
SID5	I <sub>GPIO_injection</sub>	GPIO injection current, Max for V <sub>IH</sub> > V <sub>DDD</sub> , and Min for V <sub>IL</sub> < V <sub>SS</sub>	-0.5	-	0.5	mA	Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	-	-	V	-
BID45	ESD_CDM	Electrostatic discharge charged device model	500	-	_	V	-
BID46	LU	Pin current for latch-up	-140	-	140	mA	_

## **Device Level Specifications**

All specifications are valid for –40 °C  $\leq$  T<sub>A</sub>  $\leq$  85 °C and T<sub>J</sub>  $\leq$  100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

#### Table 4. DC Specifications

Typical values measured at  $V_{DD}$  = 3.3 V and 25 °C.

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID53	V <sub>DD</sub>	Power supply input voltage	1.8	_	5.5		Internally regulated supply
SID255	V <sub>DD</sub>	Power supply input voltage (V <sub>CCD</sub> = V <sub>DDD</sub> = V <sub>DDA</sub> )	1.71	_	1.89	V	Internally unregulated supply
SID54	V <sub>CCD</sub>	Output voltage (for core logic)	_	1.8	-		_
SID55	C <sub>EFC</sub>	External regulator voltage bypass	_	0.1	-	E	X5R ceramic or better
SID56	C <sub>EXC</sub>	Power supply bypass capacitor	_	1	-	μF	ASK ceramic or better
Active M	lode, V <sub>DD</sub> = 1.8 \	to 5.5 V. Typical values measured at V	/DD = 3.3	V and 25	°C.		
SID10	I <sub>DD5</sub>	Execute from flash; CPU at 6 MHz	-	1.8	2.7		
SID16	I <sub>DD8</sub>	Execute from flash; CPU at 24 MHz	_	3.0	4.75	mA Max is at 85 °C and	Max is at 85 °C and 5.5 V
SID19	I <sub>DD11</sub>	Execute from flash; CPU at 48 MHz	_	5.4	6.85		
Sleep Mo	ode, VDDD = 1.8	V to 5.5 V (Regulator on)					
SID22	IDD17	I <sup>2</sup> C wakeup WDT, and Comparators on	_	1.7	2.2	A	6 MHZ. Max is at 85 °C and 5.5 V.
SID25	IDD20	I <sup>2</sup> C wakeup, WDT, and Comparators on.	_	2.2	2.5	mA	12 MHZ. Max is at 85 °C and 5.5 V.
Sleep Mo	ode, V <sub>DDD</sub> = 1.71	V to 1.89 V (Regulator bypassed)		ı	l .	l .	1

#### Note

Document Number: 002-00122 Rev. \*L Page 14 of 41

Usage above the absolute maximum conditions listed in Table 3 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended
periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature
Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.



## Table 4. DC Specifications (continued)

Typical values measured at  $V_{DD}$  = 3.3 V and 25 °C.

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions			
SID28	IDD23	I <sup>2</sup> C wakeup, WDT, and Comparators on	-	0.7	0.9	mA	6 MHZ. Max is at 85 °C and 5.5 V.			
SID28A	IDD23A	I <sup>2</sup> C wakeup, WDT, and Comparators on	_	1	1.2	IIIA	12 MHZ. Max is at 85 °C and 5.5 V.			
Deep Sle	Deep Sleep Mode, V <sub>DD</sub> = 1.8 V to 3.6 V (Regulator on)									
SID31	I <sub>DD26</sub>	I <sup>2</sup> C wakeup and WDT on	-	2.5	60	μΑ	Max is at 3.6 V and 85 °C.			
Deep Sle	eep Mode, V <sub>DD</sub> =	3.6 V to 5.5 V (Regulator on)								
SID34	I <sub>DD29</sub>	I <sup>2</sup> C wakeup and WDT on	_	2.5	60	μΑ	Max is at 5.5 V and 85 °C.			
Deep Sle	eep Mode, V <sub>DD</sub> =	V <sub>CCD</sub> = 1.71 V to 1.89 V (Regulator by	assed)							
SID37	I <sub>DD32</sub>	I <sup>2</sup> C wakeup and WDT on	-	2.5	65	μΑ	Max is at 1.89 V and 85 °C.			
XRES C	(RES Current									
SID307	I <sub>DD_XR</sub>	Supply current while XRES asserted	_	2	5	mA	-			

## Table 5. AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID48	F <sub>CPU</sub>	CPU frequency	DC	1	48	MHz	$1.71 \leq V_{DD} \leq 5.5$
SID49 <sup>[2]</sup>	T <sub>SLEEP</sub>	Wakeup from Sleep mode	-	0	_	ПС	_
SID50 <sup>[2]</sup>	T <sub>DEEPSLEEP</sub>	Wakeup from Deep Sleep mode	_	35	_	μs	_

Note
2. Guaranteed by characterization.



**GPIO** 

## Table 6. GPIO DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID57	V <sub>IH</sub> <sup>[3]</sup>	Input voltage high threshold	$0.7 \times V_{DDD}$	-	_		
SID58	V <sub>IL</sub>	Input voltage low threshold	-	-	$0.3 \times V_{DDD}$		CMOS Input
SID241	V <sub>IH</sub> <sup>[3]</sup>	LVTTL input, V <sub>DDD</sub> < 2.7 V	$0.7 \times V_{DDD}$	_	_		_
SID242	$V_{IL}$	LVTTL input, V <sub>DDD</sub> < 2.7 V	ı	-	$0.3 \times V_{DDD}$		_
SID243	V <sub>IH</sub> <sup>[3]</sup>	LVTTL input, V <sub>DDD</sub> ≥ 2.7 V	2.0	-	_	V	-
SID244	$V_{IL}$	LVTTL input, V <sub>DDD</sub> ≥ 2.7 V	-	-	0.8		-
SID59	$V_{OH}$	Output voltage high level	V <sub>DDD</sub> -0.6	-	_		I <sub>OH</sub> = 4 mA at 3 V V <sub>DDD</sub>
SID60	$V_{OH}$	Output voltage high level	V <sub>DDD</sub> -0.5	-	_		I <sub>OH</sub> = 1 mA at 1.8 V V <sub>DDD</sub>
SID61	$V_{OL}$	Output voltage low level	-	-	0.6		I <sub>OL</sub> = 4 mA at 1.8 V V <sub>DDD</sub>
SID62	$V_{OL}$	Output voltage low level	_	-	0.6		I <sub>OL</sub> = 10 mA at 3 V V <sub>DDD</sub>
SID62A	$V_{OL}$	Output voltage low level	_	-	0.4		I <sub>OL</sub> = 3 mA at 3 V V <sub>DDD</sub>
SID63	R <sub>PULLUP</sub>	Pull-up resistor	3.5	5.6	8.5	kΩ	-
SID64	R <sub>PULLDOWN</sub>	Pull-down resistor	3.5	5.6	8.5	NS 2	-
SID65	I <sub>IL</sub>	Input leakage current (absolute value)	_	_	2	nA	25 °C, V <sub>DDD</sub> = 3.0 V
SID66	C <sub>IN</sub>	Input capacitance	-	-	7	pF	-
SID67 <sup>[4]</sup>	V <sub>HYSTTL</sub>	Input hysteresis LVTTL	25	40	_		$V_{DDD} \ge 2.7 \text{ V}$
SID68 <sup>[4]</sup>	V <sub>HYSCMOS</sub>	Input hysteresis CMOS	0.05 × V <sub>DDD</sub>	-	_	mV	V <sub>DD</sub> < 4.5 V
SID68A <sup>[4]</sup>	V <sub>HYSCMOS5V5</sub>	Input hysteresis CMOS	200	-	_		V <sub>DD</sub> < 4.5 V
SID69 <sup>[4]</sup>	I <sub>DIODE</sub>	Current through protection diode to V <sub>DD</sub> /V <sub>SS</sub>	-	_	100	μA	-
SID69A <sup>[4]</sup>	I <sub>TOT_GPIO</sub>	Maximum total source or sink chip current	-	_	200	mA	-

V<sub>IH</sub> must not exceed V<sub>DDD</sub> + 0.2 V.
 Guaranteed by characterization.



## Table 7. GPIO AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions	
SID70	T <sub>RISEF</sub>	Rise time in fast strong mode	2	_	12	ne		
SID71	T <sub>FALLF</sub>	Fall time in fast strong mode	2	_	12	ns	3.3 V V <sub>DDD</sub> ,	
SID72	T <sub>RISES</sub>	Rise time in slow strong mode	10	_	60	-	Cload = 25 pF	
SID73	T <sub>FALLS</sub>	Fall time in slow strong mode	10	_	60	-		
SID74	F <sub>GPIOUT1</sub>	GPIO $F_{OUT}$ ; 3.3 $V \le V_{DDD} \le 5.5 V$ Fast strong mode	_	-	33			
SID75	F <sub>GPIOUT2</sub>	GPIO F <sub>OUT</sub> ; 1.71 V≤ V <sub>DDD</sub> ≤ 3.3 V Fast strong mode	_	_	16.7		90/10%, 25 pF load, 60/40 duty cycle	
SID76	F <sub>GPIOUT3</sub>	GPIO $F_{OUT}$ ; 3.3 $V \le V_{DDD} \le 5.5 V$ Slow strong mode	_	_	7	MHz		
SID245	F <sub>GPIOUT4</sub>	GPIO $F_{OUT}$ ; 1.71 $V \le V_{DDD} \le 3.3 \text{ V}$ Slow strong mode.	_	-	3.5	-		
SID246	F <sub>GPIOIN</sub>	GPIO input operating frequency; 1.71 V ≤ V <sub>DDD</sub> ≤ 5.5 V	_	ı	48		90/10% V <sub>IO</sub>	

### **XRES**

## Table 8. XRES DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID77	V <sub>IH</sub>	Input voltage high threshold	$0.7 \times V_{DDD}$	_	_	V	CMOS Input
SID78	V <sub>IL</sub>	Input voltage low threshold	_	_	$0.3 \times V_{DDD}$	V	CiviOS iriput
SID79	R <sub>PULLUP</sub>	Pull-up resistor	_	60	_	kΩ	-
SID80	C <sub>IN</sub>	Input capacitance	_	_	7	pF	-
SID81 <sup>[5]</sup>	V <sub>HYSXRES</sub>	Input voltage hysteresis	-	100	-	mV	Typical hysteresis is 200 mV for V <sub>DD</sub> > 4.5 V
SID82	I <sub>DIODE</sub>	Current through protection diode to $V_{DD}/V_{SS}$	_	_	100	μΑ	_

## Table 9. XRES AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID83 <sup>[5]</sup>	T <sub>RESETWIDTH</sub>	Reset pulse width	1	_	_	μs	_
BID194 <sup>[5]</sup>	T <sub>RESETWAKE</sub>	Wake-up time from reset release	ı	_	2.7	ms	_

Note
5. Guaranteed by characterization.



# **Analog Peripherals**

# Table 10. CTBm Opamp Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
	I <sub>DD</sub>	Opamp block current, External load					
SID269	I <sub>DD_HI</sub>	power=hi	_	1100	1850		
SID270	I <sub>DD_MED</sub>	power=med	_	550	950	μΑ	_
SID271	I <sub>DD_LOW</sub>	power=lo	_	150	350		_
	G <sub>BW</sub>	Load = 20 pF, 0.1 mA V <sub>DDA</sub> = 2.7 V					
SID272	G <sub>BW_HI</sub>	power=hi	6	_	_		
SID273	G <sub>BW_MED</sub>	power=med	3	_	_	MHz	Input and output are 0.2 V to V <sub>DDA</sub> -0.2 V
SID274	G <sub>BW_LO</sub>	power=lo	_	1	_		OIL 1 33 1 DDA 11L 1
	I <sub>OUT_MAX</sub>	$V_{DDA}$ = 2.7 V, 500 mV from rail					
SID275	I <sub>OUT_MAX_HI</sub>	power=hi	10	_	_		0 1 1: 051/
SID276	I <sub>OUT_MAX_MID</sub>	power=mid	10	_	_	mA	Output is 0.5 V V <sub>DDA</sub> -0.5 V
SID277	I <sub>OUT_MAX_LO</sub>	power=lo	_	5	_		DDA
	I <sub>OUT</sub>	V <sub>DDA</sub> = 1.71 V, 500 mV from rail					
SID278	I <sub>OUT_MAX_HI</sub>	power=hi	4	_	_		0 1 1: 051/
SID279	I <sub>OUT_MAX_MID</sub>	power=mid	4	_	_	mA	Output is 0.5 V V <sub>DDA</sub> -0.5 V
SID280	I <sub>OUT_MAX_LO</sub>	power=lo	_	2	_		DDA
	I <sub>DD_Int</sub>	Opamp block current Internal Load					
SID269_I	I <sub>DD_HI_Int</sub>	power=hi	_	1500	1700		_
SID270_I	I <sub>DD_MED_Int</sub>	power=med	_	700	900	μΑ	_
SID271_I	I <sub>DD_LOW_Int</sub>	power=lo	_	_	_		_
SIDZI I_I	G <sub>BW</sub>	$V_{DDA} = 2.7 V$	_	_	_		_
SID272_I	G <sub>BW_HI_Int</sub>	power=hi	8	-	_	MHz	Output is 0.25 V to V <sub>DDA</sub> -0.25 V
		General opamp specs for both internal and external modes				-	1
SID281	V <sub>IN</sub>	Charge-pump on, V <sub>DDA</sub> = 2.7 V	-0.05	_	V <sub>DDA</sub> -0.2		_
SID282	V <sub>CM</sub>	Charge-pump on, V <sub>DDA</sub> = 2.7 V	-0.05	_	V <sub>DDA</sub> -0.2	V	_
	V <sub>OUT</sub>	V <sub>DDA</sub> = 2.7 V		l	<u> </u>	<u>I</u>	I
SID283	V <sub>OUT_1</sub>	power=hi, Iload=10 mA	0.5	_	V <sub>DDA</sub> -0.5		_
SID284	V <sub>OUT_2</sub>	power=hi, Iload=1 mA	0.2	_	V <sub>DDA</sub> -0.2		-
SID285	V <sub>OUT_3</sub>	power=med, Iload=1 mA	0.2	_	V <sub>DDA</sub> -0.2	V	_
SID286	V <sub>OUT_4</sub>	power=lo, Iload=0.1 mA	0.2	_	V <sub>DDA</sub> -0.2	1	_



**Table 10. CTBm Opamp Specifications** (continued)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID288	V <sub>OS_TR</sub>	Offset voltage, trimmed	-1.0	±0.5	1.0		High mode, input 0 V to V <sub>DDA</sub> -0.2 V
SID288A	V <sub>OS_TR</sub>	Offset voltage, trimmed	-	±1	_	mV	Medium mode, input 0 V to V <sub>DDA</sub> -0.2 V
SID288B	V <sub>OS_TR</sub>	Offset voltage, trimmed	-	±2	_		Low mode, input 0 V to V <sub>DDA</sub> -0.2 V
SID290	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	-10	±3	10		High mode
SID290A	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	-	±10	_	μV/C	Medium mode
SID290B	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	-	±10	_		Low mode
SID291	CMRR	DC	70	80	_		Input is 0 V to V <sub>DDA</sub> -0.2 V, Output is 0.2 V to V <sub>DDA</sub> -0.2 V
SID292	PSRR	At 1 kHz, 10-mV ripple	70	85	_	dB	V <sub>DDD</sub> = 3.6 V, high-power mode, input is 0.2 V to V <sub>DDA</sub> -0.2 V
	Noise						
SID294	VN2	Input-referred, 1 kHz, power=hi	-	72	_		Input and output are at 0.2 V to V <sub>DDA</sub> -0.2 V
SID295	VN3	Input-referred, 10 kHz, power=hi	_	28	_	nV/rtHz	
SID296	VN4	Input-referred, 100 kHz, power=hi	-	15	_		
SID297	C <sub>LOAD</sub>	Stable up to max. load. Performance specs at 50 pF.	-	_	125	pF	_
SID298	SLEW_RATE	Cload = 50 pF, Power = High, V <sub>DDA</sub> = 2.7 V	6	_	_	V/µs	_
SID299	T_OP_WAKE	From disable to enable, no external RC dominating	-	_	25	μs	-
SID299A	OL_GAIN	Open Loop Gain	_	90	_	dB	-
	COMP_MODE	Comparator mode; 50 mV drive, T <sub>rise</sub> =T <sub>fall</sub> (approx.)					
SID300	TPD1	Response time; power=hi	-	150	_		
SID301	TPD2	Response time; power=med	_	500	_	ns	Input is 0.2 V to V <sub>DDA</sub> -0.2 V
SID302	TPD3	Response time; power=lo	-	2500	_		TODA V.2 V
SID303	VHYST_OP	Hysteresis	-	10	_	mV	-
SID304	WUP_CTB	Wake-up time from Enabled to Usable	-	_	25	μs	_
	Deep Sleep Mode	Mode 2 is lowest current range. Mode 1 has higher GBW.					



 Table 10. CTBm Opamp Specifications (continued)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID_DS_1	I <sub>DD_HI_M1</sub>	Mode 1, High current	_	1400	-		
SID_DS_2	I <sub>DD_MED_M1</sub>	Mode 1, Medium current	_	700	1		
SID_DS_3	I <sub>DD_LOW_M1</sub>	Mode 1, Low current	_	200	1		25 °C
SID_DS_4	I <sub>DD_HI_M2</sub>	Mode 2, High current	_	120	ı	μA	25 C
SID_DS_5	I <sub>DD_MED_M2</sub>	Mode 2, Medium current	_	60	1		
SID_DS_6	I <sub>DD_LOW_M2</sub>	Mode 2, Low current	_	15	1		
SID_DS_7	G <sub>BW_HI_M1</sub>	Mode 1, High current	_	4	1		
SID_DS_8	G <sub>BW_MED_M1</sub>	Mode 1, Medium current	_	2	1		
SID_DS_9	G <sub>BW_LOW_M1</sub>	Mode 1, Low current	_	0.5	1	MHz	20-pF load, no DC load 0.2 V to
SID_DS_10	G <sub>BW_HI_M2</sub>	Mode 2, High current	_	0.5	1	IVITIZ	V <sub>DDA</sub> -0.2 V
SID_DS_11	G <sub>BW_MED_M2</sub>	Mode 2, Medium current	_	0.2	-		
SID_DS_12	G <sub>BW_Low_M2</sub>	Mode 2, Low current	_	0.1	-		
SID_DS_13	V <sub>OS_HI_M1</sub>	Mode 1, High current	_	5	-		
SID_DS_14	V <sub>OS_MED_M1</sub>	Mode 1, Medium current	_	5	1		
SID_DS_15	V <sub>OS_LOW_M1</sub>	Mode 1, Low current	_	5	-	mV	With trim 25 °C, 0.2 V
SID_DS_16	V <sub>OS_HI_M2</sub>	Mode 2, High current	_	5	-	1110	to V <sub>DDA</sub> -0.2 V
SID_DS_17	V <sub>OS_MED_M2</sub>	Mode 2, Medium current	_	5	1		
SID_DS_18	V <sub>OS_LOW_M2</sub>	Mode 2, Low current	_	5	1		
SID_DS_19	I <sub>OUT_HI_M1</sub>	Mode 1, High current	_	10	1		0 1 1 0 5 1 1
SID_DS_20	I <sub>OUT_MED_M1</sub>	Mode 1, Medium current	_	10	1		Output is 0.5 V to V <sub>DDA</sub> -0.5 V
SID_DS_21	I <sub>OUT_LOW_M1</sub>	Mode 1, Low current	_	4	1	A	- DDA ·
SID_DS_22	I <sub>OUT_HI_M2</sub>	Mode 2, High current	_	1	ı	mA	_
SID_DS_23	I <sub>OUT_MED_M2</sub>	Mode 2, Medium current	_	1	1		_
SID_DS_24	I <sub>OUT_LOW_M2</sub>	Mode 2, Low current	_	0.5	-		

**Table 11. Comparator DC Specifications** 

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID84	V <sub>OFFSET1</sub>	Input offset voltage, Factory trim	_	_	±10		_
SID85	V <sub>OFFSET2</sub>	Input offset voltage, Custom trim	_	_	±4	mV	_
SID86	V <sub>HYST</sub>	Hysteresis when enabled	_	10	35		_
SID87	V <sub>ICM1</sub>	Input common mode voltage in normal mode	0	-	V <sub>DDD</sub> -0.1		Modes 1 and 2
SID247	V <sub>ICM2</sub>	Input common mode voltage in low power mode	0	-	V <sub>DDD</sub>	V	_
SID247A	V <sub>ICM3</sub>	Input common mode voltage in ultra low power mode	0	-	V <sub>DDD</sub> -1.15		V <sub>DDD</sub> ≥ 2.2 V at –40 °C
SID88	C <sub>MRR</sub>	Common mode rejection ratio	50	-	-	dB	V <sub>DDD</sub> ≥ 2.7V
SID88A	C <sub>MRR</sub>	Common mode rejection ratio	42	_	_	GD.	VDDD = 2.1 V

Document Number: 002-00122 Rev. \*L Page 20 of 41



## **Table 11. Comparator DC Specifications** (continued)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID89	I <sub>CMP1</sub>	Block current, normal mode	_	_	400		-
SID248	I <sub>CMP2</sub>	Block current, low power mode	_	_	100	uА	-
SID259	I <sub>CMP3</sub>	Block current in ultra low-power mode	-	-	6	μΑ	V <sub>DDD</sub> ≥ 2.2 V at –40 °C
SID90	Z <sub>CMP</sub>	DC Input impedance of comparator	35	-	_	ΜΩ	-

## Table 12. Comparator AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID91	TRESP1	Response time, normal mode, 50 mV overdrive	_	38	110	ns	-
SID258	TRESP2	Response time, low power mode, 50 mV overdrive	_	70	200		_
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	-	2.3	15	μs	V <sub>DDD</sub> ≥ 2.2 V at –40 °C

## **Table 13. Temperature Sensor Specifications**

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID93	TSENSACC	Temperature sensor accuracy	<b>-</b> 5	±1	5	°C	–40 to +85 °C

## Table 14. SAR Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SAR ADC D	C Specifications						
SID94	A_RES	Resolution	-	-	12	bits	_
SID95	A_CHNLS_S	Number of channels - single ended	-	_	16		-
SID96	A-CHNKS_D	Number of channels - differential	ı	_	4		Diff inputs use neighboring I/O
SID97	A-MONO	Monotonicity	-	-	_		Yes
SID98	A_GAINERR	Gain error	_	-	±0.1	%	With external reference.
SID99	A_OFFSET	Input offset voltage	_	_	2	mV	Measured with 1-V reference
SID100	A_ISAR	Current consumption	-	-	1	mA	-
SID101	A_VINS	Input voltage range - single ended	$V_{SS}$	_	$V_{DDA}$	V	-
SID102	A_VIND	Input voltage range - differential[	V <sub>SS</sub>	_	$V_{DDA}$		_
SID103	A_INRES	Input resistance	-	-	2.2	ΚΩ	_
SID104	A_INCAP	Input capacitance	-	-	10	pF	-
SID260	VREFSAR	Trimmed internal reference to SAR	1.188	1.2	1.212	V	-
SAR ADC A	C Specifications				•	•	·
SID106	A_PSRR	Power supply rejection ratio	70	-	_	dB	_
SID107	A_CMRR	Common mode rejection ratio	66	ı	-	ub	Measured at 1 V

Document Number: 002-00122 Rev. \*L Page 21 of 41



Table 14. SAR Specifications (continued)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID108	A_SAMP	Sample rate	-	-	1	Msps	_
SID109	A_SNR	Signal-to-noise and distortion ratio (SINAD)	65	-	-	dB	F <sub>IN</sub> = 10 kHz
SID110	A_BW	Input bandwidth without aliasing	_	-	A_samp/2	kHz	-
SID111	A_INL	Integral non linearity. V <sub>DD</sub> = 1.71 to 5.5, 1 Msps	-1.7	-	2		V <sub>REF</sub> = 1 to V <sub>DD</sub>
SID111A	A_INL	Integral non linearity. V <sub>DDD</sub> = 1.71 to 3.6, 1 Msps	-1.5	-	1.7		V <sub>REF</sub> = 1.71 to V <sub>DD</sub>
SID111B	A_INL	Integral non linearity. V <sub>DD</sub> = 1.71 to 5.5, 500 ksps	-1.5	-	1.7	LSB	V <sub>REF</sub> = 1 to V <sub>DD</sub>
SID112	A_DNL	Differential non linearity. V <sub>DD</sub> = 1.71 to 5.5, 1 Msps	-1	ı	2.2	LOD	V <sub>REF</sub> = 1 to V <sub>DD</sub>
SID112A	A_DNL	Differential non linearity. V <sub>DD</sub> = 1.71 to 3.6, 1 Msps	-1	1	2		V <sub>REF</sub> = 1.71 to V <sub>DD</sub>
SID112B	A_DNL	Differential non linearity. V <sub>DD</sub> = 1.71 to 5.5, 500 ksps	-1	-	2.2		V <sub>REF</sub> = 1 to V <sub>DD</sub>
SID113	A_THD	Total harmonic distortion	_	_	-65	dB	Fin = 10 kHz
SID261	FSARINTREF	SAR operating speed without external ref. bypass	_	_	100	ksps	12-bit resolution

## CSD

Table 15. CSD and IDAC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	ı	-	±50		$V_{DD} > 2 V$ (with ripple), 25 °C T <sub>A</sub> , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	ı	-	±25	mV	$V_{DD}$ > 1.75V (with ripple), 25 °C T <sub>A</sub> , Parasitic Capacitance (C <sub>P</sub> ) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	ı	-	4000	μΑ	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator.
SID.CSD#15	V <sub>REF</sub>	Voltage reference for CSD and Comparator	0.6	1.2	V <sub>DDA</sub> - 0.6	V	V <sub>DDA</sub> – 0.6 or 4.4, whichever is lower
SID.CSD#15A	VREF_EXT	External Voltage reference for CSD and Comparator	0.6		V <sub>DDA</sub> - 0.6	V	V <sub>DDA</sub> – 0.6 or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	-	_	1750	۸	_
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	-	_	1750	μA	_
SID308	VCSD	Voltage range of operation	1.71	_	5.5		1.8 V ±5% or 1.8 V to 5.5 V
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.6	ı	V <sub>DDA</sub> -0.6	V	V <sub>DDA</sub> – 0.6 or 4.4, whichever is lower



Table 15. CSD and IDAC Specifications (continued)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID309	IDAC1DNL	DNL	-1	_	1		_
SID310	IDAC1INL	INL	-2	_	2	LSB	INL is ±5.5 LSB for V <sub>DDA</sub> < 2 V
SID311	IDAC2DNL	DNL	<b>–1</b>	_	1		_
SID312	IDAC2INL	INL	-2	_	2		INL is ±5.5 LSB for V <sub>DDA</sub> < 2 V
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	-	_	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. V <sub>DDA</sub> > 2 V.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	-	5.4		LSB = 37.5-nA typ.
SID314A	IDAC1CRT2	Output current of IDAC1 (7 bits) in medium range	34	_	41	μA	LSB = 300-nA typ.
SID314B	IDAC1CRT3	Output current of IDAC1 (7 bits) in high range	275	-	330		LSB = 2.4-µA typ.
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	-	10.5		LSB = 75-nA typ.
SID314D	IDAC1CRT22	Output current of IDAC1(7 bits) in medium range, 2X mode	69	-	82		LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1(7 bits) in high range, 2X mode	540	_	660		LSB = 4.8-µA typ.
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	-	5.4		LSB = 37.5-nA typ.
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	_	41		LSB = 300-nA typ.
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	-	330	μA	LSB = 2.4-µA typ.
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	-	10.5	μΑ	LSB = 75-nA typ.
SID315D	IDAC2CRT22	Output current of IDAC2(7 bits) in medium range, 2X mode	69	-	82		LSB = 600-nA typ.
SID315E	IDAC2CRT32	Output current of IDAC2(7 bits) in high range, 2X mode	540	_	660		LSB = 4.8-µA typ.
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	_	10.5		LSB = 37.5-nA typ.
SID315G	IDAC3CRT23	Output current of IDAC in 8-bit mode in medium range	69	-	82	-	LSB = 300-nA typ.
SID315H	IDAC3CRT33	Output current of IDAC in 8-bit mode in high range	540	-	660		LSB = 2.4-µA typ.
SID320	IDACOFFSET	All zeroes input	_	-	1	LSB	Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode
SID321	IDACGAIN	Full-scale error less offset	-	_	±10	%	_



Table 15. CSD and IDAC Specifications (continued)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID322	IDACMISMATCH1	Mismatch between IDAC1 and IDAC2 in Low mode	-	-	9.2		LSB = 37.5-nA typ.
SID322A		Mismatch between IDAC1 and IDAC2 in Medium mode	-	-	5.6	LSB	LSB = 300-nA typ.
SID322B		Mismatch between IDAC1 and IDAC2 in High mode	_	-	6.8		LSB = 2.4-µA typ.
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	_	-	10	lie.	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	-	_	10	μs	Full-scale transition. No external load.
SID325	СМОД	External modulator capacitor.	ı	2.2	-	nF	5-V rating, X7R or NP0 cap.

Table 16. 10-bit CapSense ADC Specifications

SIDA94       A_RES       Resolution       -       -       10       bits       Auto-zeroing is required every millisecond         SIDA95       A_CHNLS_S       Number of channels - single ended       -       -       16       Defined by AMUX Bus         SIDA97       A-MONO       Monotonicity       -       -       -       16       Defined by AMUX Bus         SIDA99       A_GAINERR       Gain error       -       -       -       -       In V <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capacitance of 10 μF         SIDA99       A_OFFSET       Input offset voltage       -       -       3       mV       In V <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capacitance of 10 μF         SIDA100       A_ISAR       Current consumption       -       -       0.25       mA       -         SIDA101       A_VINS       Input voltage range - single ended       V <sub>SSA</sub> -       V <sub>DDA</sub> V       -         SIDA103       A_INRES       Input resistance       -       2.2       -       KΩ       -         SIDA104       A_INCAP       Input capacitance       -       2.2       -       KΩ       -         SIDA108       A_CONV8       Conversion time for 8-bit resolution at conversion rate = Fholk/(2^n(N+2)).       -	Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SIDA97   A-MONO   Monotonicity     Yes   -	SIDA94	A_RES	Resolution	-	-	10	bits	
SIDA98   A_GAINERR   Gain error   -   ±2   %     InV <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capacitance of 10 μF	SIDA95	A_CHNLS_S	Number of channels - single ended	-	-	16		Defined by AMUX Bus
SIDA98   A_GAINERR   Gain error   -   +2   %   V_DA_Dypass capacitance of 10 μF	SIDA97	A-MONO	Monotonicity	-	_	_	Yes	-
SIDA99       A_OFFSET       Input offset voltage       -       -       3       mV       V <sub>DDA</sub> bypass capacitance of 10 μF         SIDA100       A_ISAR       Current consumption       -       -       0.25       mA       -         SIDA101       A_VINS       Input voltage range - single ended       V <sub>SSA</sub> -       V <sub>DDA</sub> V       -         SIDA103       A_INRES       Input resistance       -       2.2       -       KΩ       -         SIDA104       A_INCAP       Input capacitance       -       20       -       pF       -         SIDA106       A_PSRR       Power supply rejection ratio       -       60       -       dB       In V <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capacitance of 10 μF         SIDA107       A_TACQ       Sample acquisition time       -       1       -       -       -       Does not include acquisition time for 10 μF         SIDA108       A_CONV8       Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^N(N+2)). Clock frequency = 48 MHz.       -       -       -       -       21.3       Does not include acquisition time.         SIDA108       A_CONV10       Conversion rate = Fhclk/(2^N(N+2)). Clock frequency = 48 MHz.       -       -       -       -       -	SIDA98	A_GAINERR	Gain error	-	-	±2	%	V <sub>DDA</sub> bypass
SIDA101   A_VINS   Input voltage range - single ended   V <sub>SSA</sub>   - V <sub>DDA</sub>   V   -	SIDA99	A_OFFSET	Input offset voltage	1	-	3	mV	V <sub>DDA</sub> bypass
SIDA103 A_INRES Input resistance	SIDA100	A_ISAR	Current consumption	ı	_	0.25	mA	_
SIDA104 A_INCAP Input capacitance	SIDA101	A_VINS	Input voltage range - single ended	$V_{SSA}$	_	$V_{DDA}$	V	-
SIDA106 A_PSRR Power supply rejection ratio - 60 - dB In V <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capacitance of 10 µF  SIDA107 A_TACQ Sample acquisition time - 1 -   Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^{(N+2))}. Clock frequency = 48 MHz.  SIDA108 A_CONV10 Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^{(N+2))}. Clock frequency = 48 MHz.  Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^{(N+2))}. Clock frequency = 48 MHz.  SIDA109 A_SND Signal-to-noise and Distortion ratio (SINAD)  SIDA109 A_SND Signal-to-noise and Distortion ratio (SINAD)  - 61 - dB With 10-Hz input sine wave, external 2.4-V reference, V <sub>REF</sub> (2.4 V) mode	SIDA103	A_INRES	Input resistance	-	2.2	_	ΚΩ	-
SIDA106 A_PSRR Power supply rejection ratio — 60 — dB V <sub>DDA</sub> bypass capacitance of 10 µF  SIDA107 A_TACQ Sample acquisition time — 1 — — — — — — — — — — — — — — — — —	SIDA104	A_INCAP	Input capacitance	_	20	_	pF	-
SIDA108 A_CONV8 Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.  Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.  Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.  Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.  SIDA109 A_SND Signal-to-noise and Distortion ratio (SINAD)  Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.  Does not include acquisition time.  A_SND Signal-to-noise and Distortion ratio  Clock frequency = 48 MHz.  85.3  Mith 10-Hz input sine wave, external 2.4-V reference, V <sub>REF</sub> (2.4 V) mode	SIDA106	A_PSRR	Power supply rejection ratio	-	60	_	dB	V <sub>DDA</sub> bypass
SIDA108 A_CONV8   Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^(N+2)).   -   -   21.3     sition time. Equivalent to 44.8 ksps including acquisition time.    SIDA108A   A_CONV10   Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)).   -   -   85.3   Does not include acquisition time.    SIDA109   A_SND   Signal-to-noise and Distortion ratio (SINAD)   -   61   -   dB   With 10-Hz input sine wave, external 2.4-V reference, VREF (2.4 V) mode	SIDA107	A_TACQ	Sample acquisition time	_	1	_		-
SIDA108A A_CONV10 Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)).	SIDA108	A_CONV8	conversion rate = Fhclk/(2^(N+2)).	-	-	21.3	μs	sition time. Equivalent to 44.8 ksps including
SIDA109 A_SND Signal-to-noise and Distortion ratio (SINAD) - 61 - dB wave, external 2.4-V reference, V <sub>REF</sub> (2.4 V) mode	SIDA108A	A_CONV10	conversion rate = Fhclk/(2^(N+2)).	-	-	85.3		sition time. Equivalent to 11.6 ksps including
SIDA110 A_BW Input bandwidth without aliasing 22.4 KHz 8-bit resolution	SIDA109	A_SND		-	61	-	dB	wave, external 2.4-V reference, V <sub>REF</sub> (2.4 V)
	SIDA110	A_BW	Input bandwidth without aliasing	-	_	22.4	KHz	8-bit resolution



## Table 16. 10-bit CapSense ADC Specifications (continued)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SIDA111	A_INL	Integral Non Linearity. 1 ksps	-	_	2	LSB	V <sub>REF</sub> = 2.4 V or greater
SIDA112	A_DNL	Differential Non Linearity. 1 ksps	_	-	1	LOD	-

## **Digital Peripherals**

Timer Counter Pulse-Width Modulator (TCPWM)

## **Table 17. TCPWM Specifications**

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID.TCPWM.1	ITCPWM1	Block current consumption at 3 MHz	_	_	45		
SID.TCPWM.2	ITCPWM2	Block current consumption at 12 MHz	_	_	155	μΑ	All modes (TCPWM)
SID.TCPWM.2A	ITCPWM3	Block current consumption at 48 MHz	_	_	650		
SID.TCPWM.3	TCPWM <sub>FREQ</sub>	Operating frequency	-	-	Fc	MHz	Fc max = CLK_SYS Maximum = 48 MHz
SID.TCPWM.4	TPWM <sub>ENEXT</sub>	Input trigger pulse width	2/Fc	_	_		For all trigger events <sup>[6]</sup>
SID.TCPWM.5	TPWM <sub>EXT</sub>	Output trigger pulse widths	2/Fc	_	_		Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) outputs
SID.TCPWM.5A	TC <sub>RES</sub>	Resolution of counter	1/Fc	-	-	ns	Minimum time between successive counts
SID.TCPWM.5B	PWM <sub>RES</sub>	PWM resolution	1/Fc	-	-		Minimum pulse width of PWM Output
SID.TCPWM.5C	Q <sub>RES</sub>	Quadrature inputs resolution	1/Fc	_	ı		Minimum pulse width between Quadrature phase inputs

РC

# Table 18. Fixed I<sup>2</sup>C DC Specifications<sup>[7]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID149	I <sub>I2C1</sub>	Block current consumption at 100 kHz	-	_	50		_
SID150	I <sub>I2C2</sub>	Block current consumption at 400 kHz	-	_	135		_
SID151	I <sub>I2C3</sub>	Block current consumption at 1 Mbps	-	_	310	μΑ	_
SID152	I <sub>I2C4</sub>	I <sup>2</sup> C enabled in Deep Sleep mode	_	_	1.4		

# Table 19. Fixed I<sup>2</sup>C AC Specifications<sup>[7]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID153	F <sub>I2C1</sub>	Bit rate	-	-	1	Msps	_

## Table 20. SPI DC Specifications<sup>[7]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID163	ISPI1	Block current consumption at 1 Mbps	_	_	360		_
SID164	ISPI2	Block current consumption at 4 Mbps	_	_	560	μA	_
SID165	ISPI3	Block current consumption at 8 Mbps	_	_	600		-

#### Notes

6. Trigger events can be Stop, Start, Reload, Count, Capture, or Kill depending on which mode of operation is selected.7. Guaranteed by characterization.



Table 21. SPI AC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions				
SID166	FSPI	SPI Operating frequency (Master; 6X Oversampling)	-	_	8	MHz	SID166				
Fixed SPI I	Fixed SPI Master Mode AC Specifications										
SID167	TDMO	MOSI Valid after SClock driving edge	_	_	15		-				
SID168	TDSI	MISO Valid before SClock capturing edge	20	_	_	ns	Full clock, late MISO sampling				
SID169	ТНМО	Previous MOSI data hold time	0	_	_		Referred to Slave capturing edge				
Fixed SPI	Slave Mode AC	Specifications									
SID170	TDMI	MOSI Valid before Sclock Capturing edge	40	_	_		-				
SID171	TDSO	MISO Valid after Sclock driving edge	_	_	42 + 3*Tcpu		T <sub>CPU</sub> = 1/F <sub>CPU</sub>				
SID171A	TDSO_EXT	MISO Valid after Sclock driving edge in Ext. Clk mode	_	_	48	ns	-				
SID172	THSO	Previous MISO data hold time	0	_	_		-				
SID172A	TSSELSSCK	SSEL Valid to first SCK Valid edge	100	_	-		-				

## Table 22. UART DC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID160	I <sub>UART1</sub>	Block current consumption at 100 Kbps	1	-	55	μA	-
SID161	I <sub>UART2</sub>	Block current consumption at 1000 Kbps	_	_	312	μΑ	-

# Table 23. UART AC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID162	F <sub>UART</sub>	Bit rate	_	-	1	Mbps	-

# Table 24. LCD Direct Drive DC Specifications $^{[8]}$

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID154	I <sub>LCDLOW</sub>	Operating current in low power mode	ı	5	1	μΑ	16 × 4 small segment disp. at 50 Hz
SID155	C <sub>LCDCAP</sub>	LCD capacitance per segment/common driver	-	500	5000	pF	-
SID156	LCD <sub>OFFSET</sub>	Long-term segment offset	_	20	_	mV	_
SID157	I <sub>LCDOP1</sub>	LCD system operating current Vbias = 5 V	1	2		mA	32 × 4 segments. 50 Hz. 25 °C
SID158	I <sub>LCDOP2</sub>	LCD system operating current Vbias = 3.3 V	ı	2	ı	Ш	32 × 4 segments. 50 Hz. 25 °C

Page 26 of 41 Document Number: 002-00122 Rev. \*L

**Note**8. Guaranteed by characterization.



## Table 25. LCD Direct Drive AC Specifications<sup>[10]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID159	F <sub>LCD</sub>	LCD frame rate	10	50	150	Hz	_

### Memory

## Table 26. Flash DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID173	$V_{PE}$	Erase and program voltage	1.71	-	5.5	<b>V</b>	-

### Table 27. Flash AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID174	T <sub>ROWWRITE</sub> <sup>[9]</sup>	Row (block) write time (erase and program)	-	_	20		Row (block) = 128 bytes
SID175	T <sub>ROWERASE</sub> <sup>[9]</sup>	Row erase time	-	-	16	ms	_
SID176	T <sub>ROWPROGRAM</sub> <sup>[9]</sup>	Row program time after erase	_	-	4		-
SID178	T <sub>BULKERASE</sub> <sup>[9]</sup>	Bulk erase time (64 KB)	_	-	35		-
SID180 <sup>[10]</sup>	T <sub>DEVPROG</sub> <sup>[9]</sup>	Total device program time	-	_	7	Seconds	-
SID181 <sup>[10]</sup>	F <sub>END</sub>	Flash endurance	100 K	-	_	Cycles	-
SID182 <sup>[10]</sup>	F <sub>RET</sub>	Flash retention. $T_A \le 55$ °C, 100 K P/E cycles	20	_	_	Years	_
SID182A <sup>[10]</sup>	_	Flash retention. $T_A \le 85$ °C, 10 K P/E cycles	10	_	_	Teals	_
SID256	TWS48	Number of Wait states at 48 MHz	2	_	-		CPU execution from
SID257	TWS24	Number of Wait states at 24 MHz	1	_	_		Flash

## **System Resources**

Power-on Reset (POR)

#### Table 28. Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID.CLK#6	SR_POWER_UP	Power supply slew rate	1	1	67	V/ms	At power-up
SID185 <sup>[10]</sup>	V <sub>RISEIPOR</sub>	Rising trip voltage	0.80	1	1.5	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-
SID186 <sup>[10]</sup>	V <sub>FALLIPOR</sub>	Falling trip voltage	0.70	1	1.4	V	_

## Table 29. Brown-out Detect (BOD) for V<sub>CCD</sub>

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID190 <sup>[10]</sup>	V <sub>FALLPPOR</sub>	BOD trip voltage in active and sleep modes	1.48	ı	1.62	V	-
SID192 <sup>[10]</sup>	V <sub>FALLDPSLP</sub>	BOD trip voltage in Deep Sleep	1.11	1	1.5		-

#### Notes

It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied
on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs.
Make certain that these are not inadvertently activated.

<sup>10.</sup> Guaranteed by characterization.



### SWD Interface

## Table 30. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID213	F_SWDCLK1	$3.3~V \leq V_{DD} \leq 5.5~V$	ı	I	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	$1.71 \text{ V} \le \text{V}_{DD} \le 3.3 \text{ V}$	-	ı	7	IVITZ	SWDCLK ≤ 1/3 CPU clock frequency
SID215 <sup>[11]</sup>	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	_	_		_
SID216 <sup>[11]</sup>	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	_	_	no	_
SID217 <sup>[11]</sup>	T_SWDO_VALID	T = 1/f SWDCLK	_	-	0.5*T	ns	_
SID217A <sup>[11]</sup>	T_SWDO_HOLD	T = 1/f SWDCLK	1	-	_		_

Internal Main Oscillator

### Table 31. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID218	I <sub>IMO1</sub>	IMO operating current at 48 MHz	_	-	250	uА	_
SID219	I <sub>IMO2</sub>	IMO operating current at 24 MHz	_	-	180	μΑ	_

## Table 32. IMO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID223		Frequency variation at 24, 32, and 48 MHz (trimmed)	_	_	±2	%	-
SID226	T <sub>STARTIMO</sub>	IMO startup time	_	_	7	μs	_
SID228	T <sub>JITRMSIMO2</sub>	RMS jitter at 24 MHz	_	145	_	ps	_

Internal Low-Speed Oscillator

## Table 33. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID231 <sup>[11]</sup>	I <sub>ILO1</sub>	ILO operating current	_	0.3	1.05	μΑ	_

## Table 34. ILO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID234 <sup>[11]</sup>	T <sub>STARTILO1</sub>	ILO startup time	-	_	2	ms	_
SID236 <sup>[11]</sup>	T <sub>ILODUTY</sub>	ILO duty cycle	40	50	60	%	_
SID237	F <sub>ILOTRIM1</sub>	ILO frequency range	20	40	80	kHz	_

#### Note

<sup>11.</sup> Guaranteed by characterization.



## Table 35. Watch Crystal Oscillator (WCO) Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID398	FWCO	Crystal Frequency	-	32.768	1	kHz	_
SID399	FTOL	Frequency tolerance	_	50	250	ppm	With 20-ppm crystal
SID400	ESR	Equivalent series resistance	_	50	_	kΩ	-
SID401	PD	Drive Level	_	-	1	μW	-
SID402	TSTART	Startup time	_	_	500	ms	-
SID403	CL	Crystal Load Capacitance	6	_	12.5	pF	-
SID404	C0	Crystal Shunt Capacitance	_	1.35	_		-
SID405	IWCO1	Operating Current (high power mode)	_	-	8	μΑ	-
SID406	IWCO2	Operating Current (low power mode)	_	_	1		_

## **Table 36. External Clock Specifications**

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID305 <sup>[12]</sup>	ExtClkFreq	External clock input frequency	0	1	48	MHz	-
SID306 <sup>[12]</sup>	ExtClkDuty	Duty cycle; measured at V <sub>DD/2</sub>	45	-	55	%	_

## Table 37. Block Specs

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID262 <sup>[12]</sup>	T <sub>CLKSWITCH</sub>	System clock source switching time	3	_	4	Periods	_

## Table 38. Smart I/O Pass-through Time (Delay in Bypass Mode)

Spec ID	Parameter	Description	Min	Тур	Max	Unit	Details/Conditions
SID252	IPRG BYPASS	Max delay added by Smart I/O in bypass mode	-	ı	1.6	ns	-

**Note** 12. Guaranteed by characterization.



# **Ordering Information**

The marketing part numbers for the PSoC 4100S family are listed in the following table.

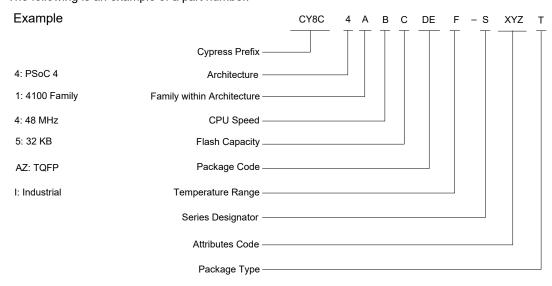
								Featur	es							Р	ackag	е	
Category	MPN	Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	Opamp (CTBm)	CSD	10-bit CSD ADC	12-bit SAR ADC	ADC Sample Rate	LP Comparators	TCPWM Blocks	SCB Blocks	Smart I/Os	GPIO	35-WLCSP (0.35mm pitch)	32-QFN	40-QFN	48-TQFP	44-TQFP
	CY8C4124FNI-S403(T)	24	16	4	2	0	1	0		2	5	2	8	31	Х				
	CY8C4124FNI-S413(T)	24	16	4	2	1	1	0		2	5	2	16	31	Х				
	CY8C4124LQI-S412(T)	24	16	4	2	1	1	0		2	5	2	16	27		Х			
	CY8C4124LQI-S413(T)	24	16	4	2	1	1	0		2	5	2	16	34			Х		
4124	CY8C4124AZI-S413(T)	24	16	4	2	1	1	0		2	5	2	16	36				Х	
	CY8C4124FNI-S433(T)	24	16	4	2	1	1	1	806 ksps	2	5	2	16	31	Х				
	CY8C4124LQI-S432(T)	24	16	4	2	1	1	1	806 ksps	2	5	2	16	27		Х			
	CY8C4124LQI-S433(T)	24	16	4	2	1	1	1	806 ksps	2	5	2	16	34			Х		
	CY8C4124AZI-S433(T)	24	16	4	2	1	1	1	806 ksps	2	5	2	16	36				Х	
	CY8C4125FNI-S423(T)	24	32	4	2	0	1	1	806 ksps	2	5	2	16	31	Х				
	CY8C4125LQI-S422(T)	24	32	4	2	0	1	1	806 ksps	2	5	2	16	27		Χ			
	CY8C4125LQI-S423(T)	24	32	4	2	0	1	1	806 ksps	2	5	2	16	34			Х		
	CY8C4125AZI-S423(T)	24	32	4	2	0	1	1	806 ksps	2	5	2	16	36				Х	
	CY8C4125AXI-S423	24	32	4	2	0	1	1	806 ksps	2	5	2	16	36					Х
	CY8C4125FNI-S413(T)	24	32	4	2	1	1	0		2	5	2	16	31	Х				
4125	CY8C4125LQI-S412(T)	24	32	4	2	1	1	0		2	5	2	16	27		Х			
4120	CY8C4125LQI-S413(T)	24	32	4	2	1	1	0		2	5	2	16	34			Х		
	CY8C4125AZI-S413(T)	24	32	4	2	1	1	0		2	5	2	16	36				Х	
	CY8C4125FNI-S433(T)	24	32	4	2	1	1	1	806 ksps	2	5	2	16	31	Х				
	CY8C4125LQI-S432	24	32	4	2	1	1	1	806 ksps	2	5	2	16	27		Χ			
	CY8C4125LQI-S433	24	32	4	2	1	1	1	806 ksps	2	5	2	16	34			Х		
	CY8C4125AZI-S433(T)	24	32	4	2	1	1	1	806 ksps	2	5	2	16	36				Х	
	CY8C4125AXI-S433	24	32	4	2	1	1	1	806 ksps	2	5	2	16	36					Х
	CY8C4126AZI-S423(T)	24	64	8	2	0	1	1	806 ksps	2	5	3	16	36				Х	
4126	CY8C4126AXI-S423	24	64	8	2	0	1	1	806 ksps	2	5	3	16	36					Х
20	CY8C4126AZI-S433(T)	24	64	8	2	1	1	1	806 ksps	2	5	3	16	36				Х	
	CY8C4126AXI-S433	24	64	8	2	1	1	1	806 ksps	2	5	3	16	36					Х
	CY8C4145AZI-S423(T)	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36				Х	
4145	CY8C4145AXI-S423	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36					Х
	CY8C4145AXI-S433	48	32	4	2	1	1	1	1 Msps	2	5	2	16	36					Х
	CY8C4146FNI-S423(T)	48	64	8	2	0	1	1	1 Msps	2	5	3	16	31	Х				
	CY8C4146LQI-S422(T)	48	64	8	2	0	1	1	1 Msps	2	5	3	16	27		Х			
	CY8C4146LQI-S423(T)	48	64	8	2	0	1	1	1 Msps	2	5	3	16	34			Х		
	CY8C4146AZI-S423(T)	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36				Х	
4146	CY8C4146AXI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36					Х
	CY8C4146FNI-S433(T)	48	64	8	2	1	1	1	1 Msps	2	5	3	16	31	Х				
	CY8C4146LQI-S432(T)	48	64	8	2	1	1	1	1 Msps	2	5	3	16	27		Х			
	CY8C4146LQI-S433(T)	48	64	8	2	1	1	1	1 Msps	2	5	3	16	34			Х		
	CY8C4146AZI-S433(T)	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36				Х	
	CY8C4146AXI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36					Х



The nomenclature used in the preceding table is based on the following part numbering convention:

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
Α	Family	1	4100 Family
В	CPU Speed	2	24 MHz
В	CFO Speed	4	48 MHz
		4	16 KB
С	Flash Capacity	5	32 KB
	Гіазії Сарасіту	6	64 KB
		7	128 KB
		AX	TQFP (0.8mm pitch)
		AZ	TQFP (0.5mm pitch)
DE	Package Code	LQ	QFN
		PV	SSOP
		FN	CSP
F	Temperature Range	I	Industrial
		S	S-Series
S	Series Designator	М	M-Series
			L-Series
XYZ	Attributes Code	000-999	Code of feature set in the specific family
Т	Package Type		Tray
!	Package Type	Т	Tape and Reel

The following is an example of a part number.





# **Packaging**

The PSoC 4100S will be offered in 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball WLCSP packages. Table 39 provides the package dimensions and Cypress drawing numbers.

Table 39. Package List

Spec ID	Package	Description	Package Dwg
BID20	48-pin TQFP	7 × 7 × 1.4-mm height with 0.5-mm pitch	51-85135
BID20A	44-pin TQFP	10 × 10 × 1.6-mm height with 0.8-mm pitch	51-85064
BID27	40-pin QFN	6 × 6 × 0.6-mm height with 0.5-mm pitch	001-80659
BID34A	32-pin QFN	5 × 5 × 0.6-mm height with 0.5-mm pitch	001-42168
BID34D	35-ball WLCSP	2.6 × 2.1 × 0.48-mm height with 0.35-mm pitch	002-09958

**Table 40. Package Thermal Characteristics** 

Parameter	Description	Package	Min	Тур	Max	Unit	Details/Conditions
ТА	Operating ambient temperature	_	-40	25	85	°C	_
TJ	Operating junction temperature	_	-40	-	100	C	_
Тја	Package θ <sub>JA</sub>	48-pin TQFP	-	74.8	-		_
Tjc	Package θ <sub>JC</sub>	48-pin TQFP	-	35.7	-		_
Тја	Package θ <sub>JA</sub>	44-pin TQFP	-	57.2	-		_
Tjc	Package θ <sub>JC</sub>	44-pin TQFP	-	17.5	-		_
Тја	Package θ <sub>JA</sub>	40-pin QFN	-	17.8	-	°C/Watt	_
TJC	Package θ <sub>JC</sub>	40-pin QFN	-	2.8	-	C/vvall	_
Тја	Package θ <sub>JA</sub>	32-pin QFN	-	19.9	-		_
TJC	Package θ <sub>JC</sub>	32-pin QFN	-	4.3	-		_
TJA	Package θ <sub>JA</sub>	35-ball WLCSP	-	43	-		-
Tjc	Package θ <sub>JC</sub>	35-ball WLCSP	-	0.3	-		_

## Table 41. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All	260 °C	30 seconds

Table 42. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020

Package	MSL
All except WLCSP	MSL 3
35-ball WLCSP	MSL 1

Document Number: 002-00122 Rev. \*L Page 32 of 41



## **Package Diagrams**

Figure 7. 48-pin TQFP Package Outline

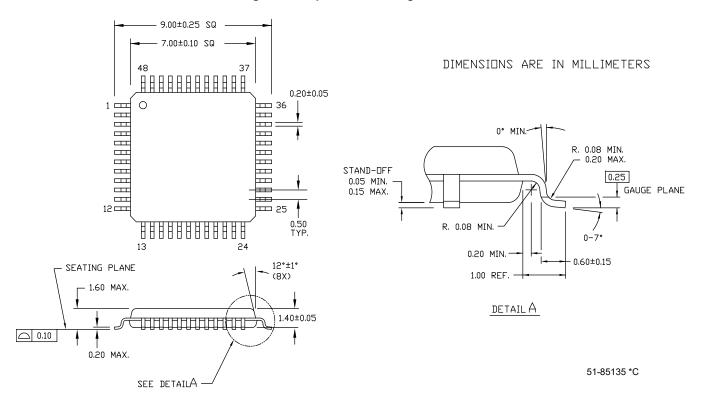
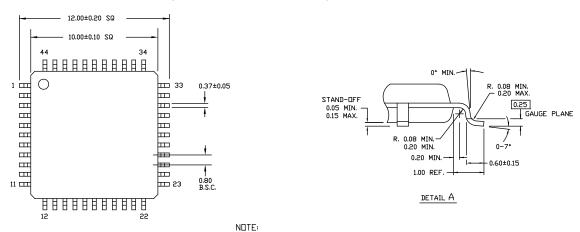


Figure 8. 44-pin TQFP Package Outline



- SEATING PLANE

  1.60 MAX.

  1.40±0.05

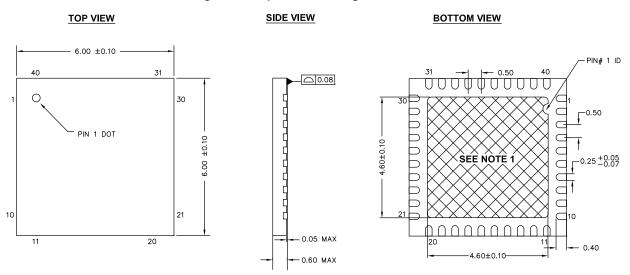
  0.20 MAX.

  SEE DETAILA
- 1. JEDEC STD REF MS-026
- 2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH
  MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.0098 in (0.25 mm) PER SIDE
  BODY LENGTH DIMENSIONS ARE MAX PLASTIC BODY SIZE INCLUDING MOLD MISMATCH
- 3. DIMENSIONS IN MILLIMETERS

51-85064 \*G



Figure 9. 40-pin QFN Package Outline



## NOTES:

- 1. XX HATCH AREA IS SOLDERABLE EXPOSED PAD
- 2. REFERENCE JEDEC # MO-248
- 3. PACKAGE WEIGHT: 68 ±2 mg
- 4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 \*A

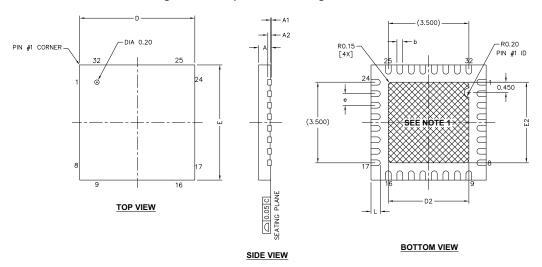


Figure 10. 32-pin QFN Package Outline

SYMBOL	DIMENSIONS				
STIVIBOL	MIN.	NOM.	MAX.		
Α	0.50	0.55	0.60		
A1	-	0.020	0.045		
A2	0.15 BSC				
D	4.90	5.00	5.10		
D2	3.40	3.50	3.60		
E	4.90	5.00	5.10		
E2	3.40	3.50	3.60		
L	0.30	0.40	0.50		
b	0.18	0.25	0.30		
е	0.50 TYP				

#### NOTES:

- 1. MATCH AREA IS SOLDERABLE EXPOSED PAD
- 2. BASED ON REF JEDEC # MO-248
- 3. PACKAGE WEIGHT: 0.0388g
- 4. DIMENSIONS ARE IN MILLIMETERS

001-42168 \*F



SIDE VIEW TOP VIEW BOTTOM VIEW 0.369+0.03 PIN #1 MARK A1 BALL CORNER 2 3 4 5 6 7 △ 0.05 A  $\bigcirc \oplus \Diamond \bigcirc \bigcirc$  $\oplus$   $\circ$   $\circ$   $\circ$   $\circ$   $\circ$ 띪 EJ 몽 0000000 D  $\oplus \oplus \bigcirc \oplus \bigcirc \bigcirc \oplus$  $0.241^{+0.03}_{-0}$ eD -0.241+0.03 D1

Figure 11. 35-Ball WLCSP Package Outline

0.44001		DIMENSIONS				
SYMBOL	MIN.	NOM.	MAX.			
Α	-	-	0.482			
A1	0.141	0.157	0.173			
D	2.557	2.582	2.607			
E	2.072	2.097	2.122			
D1	2.10 BSC					
E1	1.40 BSC					
MD	7					
ME		5				
N		35				
Øь	0.19	0.22	0.25			
eD	-	0.35	-			
eE	- 0.35 -					
SD	0					
SE	0.02 BSC					

#### NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. JEDEC PUBLICATION 95; DESIGN GUIDE 4.18.

002-09958 \*D



# **Acronyms**

Table 43. Acronyms Used in this Document

Acronym	Description	
abus	analog local bus	
ADC	analog-to-digital converter	
AG	analog global	
АНВ	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus	
ALU	arithmetic logic unit	
AMUXBUS	analog multiplexer bus	
API	application programming interface	
APSR	application program status register	
ARM <sup>®</sup>	advanced RISC machine, a CPU architecture	
ATM	automatic thump mode	
BW	bandwidth	
CAN	Controller Area Network, a communications protocol	
CMRR	common-mode rejection ratio	
CPU	central processing unit	
CRC	cyclic redundancy check, an error-checking protocol	
DAC	digital-to-analog converter, see also IDAC, VDAC	
DFB	digital filter block	
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.	
DMIPS	Dhrystone million instructions per second	
DMA	direct memory access, see also TD	
DNL	differential nonlinearity, see also INL	
DNU	do not use	
DR	port write data registers	
DSI	digital system interconnect	
DWT	data watchpoint and trace	
ECC	error correcting code	
ECO	external crystal oscillator	
EEPROM	electrically erasable programmable read-only memory	
EMI	electromagnetic interference	
EMIF	external memory interface	
EOC	end of conversion	
EOF	end of frame	
EPSR	execution program status register	
ESD	electrostatic discharge	

Table 43. Acronyms Used in this Document (continued)

Acronym	Description
ETM	embedded trace macrocell
FIR	finite impulse response, see also IIR
FPB	flash patch and breakpoint
FS	full-speed
GPIO	general-purpose input/output, applies to a PSoC pin
HVI	high-voltage interrupt, see also LVI, LVD
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
I <sup>2</sup> C, or IIC	Inter-Integrated Circuit, a communications protocol
IIR	infinite impulse response, see also FIR
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
I/O	input/output, see also GPIO, DIO, SIO, USBIO
IPOR	initial power-on reset
IPSR	interrupt program status register
IRQ	interrupt request
ITM	instrumentation trace macrocell
LCD	liquid crystal display
LIN	Local Interconnect Network, a communications protocol.
LR	link register
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVI	low-voltage interrupt, see also HVI
LVTTL	low-voltage transistor-transistor logic
MAC	multiply-accumulate
MCU	microcontroller unit
MISO	master-in slave-out
NC	no connect
NMI	nonmaskable interrupt
NRZ	non-return-to-zero
NVIC	nested vectored interrupt controller
NVL	nonvolatile latch, see also WOL
opamp	operational amplifier
PAL	programmable array logic, see also PLD

Document Number: 002-00122 Rev. \*L Page 37 of 41



Table 43. Acronyms Used in this Document (continued)

Acronym	Description			
PC	program counter			
PCB	printed circuit board			
PGA	programmable gain amplifier			
PHUB	peripheral hub			
PHY	physical layer			
PICU	port interrupt control unit			
PLA	programmable logic array			
PLD	programmable logic device, see also PAL			
PLL	phase-locked loop			
PMDD	package material declaration data sheet			
POR	power-on reset			
PRES	precise power-on reset			
PRS	pseudo random sequence			
PS	port read data register			
PSoC <sup>®</sup>	Programmable System-on-Chip™			
PSRR	power supply rejection ratio			
PWM	pulse-width modulator			
RAM	random-access memory			
RISC	reduced-instruction-set computing			
RMS	root-mean-square			
RTC	real-time clock			
RTL	register transfer language			
RTR	remote transmission request			
RX	receive			
SAR	successive approximation register			
SC/CT	switched capacitor/continuous time			
SCL	I <sup>2</sup> C serial clock			
SDA	I <sup>2</sup> C serial data			
S/H	sample and hold			
SINAD	signal to noise and distortion ratio			
SIO	special input/output, GPIO with advanced features. See GPIO.			
SOC	start of conversion			
SOF	start of frame			
SPI	Serial Peripheral Interface, a communications protocol			
SR	slew rate			
SRAM	static random access memory			
SRES	software reset			
SWD	serial wire debug, a test protocol			

Table 43. Acronyms Used in this Document (continued)

Acronym	Description		
SWV	single-wire viewer		
TD	transaction descriptor, see also DMA		
THD	total harmonic distortion		
TIA	transimpedance amplifier		
TRM	technical reference manual		
TTL	transistor-transistor logic		
TX	transmit		
UART	Universal Asynchronous Transmitter Receiver, communications protocol		
UDB	universal digital block		
USB	Universal Serial Bus		
USBIO	USB input/output, PSoC pins used to connect to a USB port		
VDAC	voltage DAC, see also DAC, IDAC		
WDT	watchdog timer		
WOL	write once latch, see also NVL		
WRES	watchdog timer reset		
XRES	external reset I/O pin		
XTAL	crystal		

Document Number: 002-00122 Rev. \*L Page 38 of 41



# **Document Conventions**

## **Units of Measure**

## Table 44. Units of Measure

Symbol	Unit of Measure			
°C	degrees Celsius			
dB	decibel			
fF	femto farad			
Hz	hertz			
KB	1024 bytes			
kbps	kilobits per second			
Khr	kilohour			
kHz	kilohertz			
kΩ	kilo ohm			
ksps	kilosamples per second			
LSB	least significant bit			
Mbps	megabits per second			
MHz	megahertz			
ΜΩ	mega-ohm			
Msps	megasamples per second			
μΑ	microampere			
μF	microfarad			
μH	microhenry			
μs	microsecond			
μV	microvolt			
μW	microwatt			
mA	milliampere			
ms	millisecond			
mV	millivolt			
nA	nanoampere			
ns	nanosecond			
nV	nanovolt			
Ω	ohm			
pF	picofarad			
ppm	parts per million			
ps	picosecond			
S	second			
sps	samples per second			
sqrtHz	square root of hertz			
V	volt			



# **Revision History**

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	4883809	WKA	08/28/2015	New datasheet
*A	4992376	WKA	10/30/2015	Updated Pinouts. Added $V_{DDD} \ge 2.2V$ at $-40~^{\circ}C$ under Conditions for specs SID247A, SID90, SID92. Updated Table 16. Updated Ordering Information.
*B	5037826	SLAN	12/08/2015	Changed datasheet status to Preliminary
*C	5060691	WKA	12/22/2015	Updated SCBs from 2 to 3. Updated SRAM size to 8 KB. Changed WLCSP package to 35-ball WLCSP. Updated Pin List and Alternate Pin Functions. Updated Ordering Information.
*D	5139206	WKA	02/16/2016	Added Errata. Added 35 WLCSP package details. Updated theta J <sub>A</sub> and J <sub>C</sub> values for all packages. Updated copyright information at the end of the document.
*E	5173961	WKA	03/15/2016	Updated values for SID79, BID194. SID175, and SID176. Updated CSD and IDAC Specifications. Updated 10-bit CapSense ADC Specifications.
*F	5330930	WKA	07/27/2016	Updated CSD and IDAC Specifications. Updated 10-bit CapSense ADC Specifications. Removed errata.
*G	5473409	WKA	10/13/2016	Added 44 TQFP pin and package details.
*H	5561833	WKA	01/09/2017	Updated Figure 4. Changed PRGIO references to Smart I/O. Updated DC Specifications. Updated Ordering Information.
*	5713158	WKA	04/26/2017	Updated 35-ball WLCSP package diagram. Updated the Cypress logo.
*J	6069924	WKA	02/14/2018	Updated Sales page. Updated Features. Updated Development Support. Updated Ordering Information. Updated Figure 2 and Figure 3. Updated Figure 10 in Packaging (spec 001-42168 *E to *F). Updated Table 2.
*K	6120525	WKA	04/03/2018	Updated Clock Diagram to show Watchdog details and clock divider informat
*L	6348123	WKA	10/30/2018	Updated 32-bit MCU subsystem feature list. Corrected typo in the block diagram. Updated Watch Crystal Oscillator (WCO). Corrected typos in CTBm Opamp Specifications. Updated values for SID260. Updated Conditions for SID.CSD#15, SID.CSD#15A, and SID308A. Updated min and max values for SID172A.



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Document Number: 002-00122 Rev. \*L Revised October 30, 2018 Page 41 of 41